

Claims:

1. In a method for applying a thin-walled, flat substrate to an assembly carrier (6) with a protective layer (5), the improvement comprising:

with respect to the protective layer (5) arranging the substrate at a spacing and curved in a convex manner, contacting the substrate (4) with the protective layer (5), and laying the substrate (4) over the entire protective layer (5) from a contact point towards an edge of the substrate.

2. In the method according to claim 1, wherein when laid the substrate (4) applies a constant pressure on the protective layer (5).

3. In the method according to claim 2, wherein a pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

4. In the method according to claim 3, wherein a formation of the substrate arching and a detachment of the substrate from the carrying body (2) are achieved by controlling a pressure of the medium in a cavity between the substrate (4) and the carrying body (2).

5. In the method according to claim 4, wherein a carrying body (2) moveable relative to the assembly carrier (6) and a portion (8) facing the protective layer (5) carries the substrate (4) and has a plurality of flow apertures (3, 7) for accommodating the pressure medium.

6. In the method according to claim 5, wherein the portion (8) is preferably planar and the flow apertures (3, 7) are centrally formed ducts and circumferential grooves.

7. In the method according to claim 6, wherein the flow apertures (3, 7) are configured as overpressure lines and the grooves are configured as negative pressure lines.

8. In the method according to claim 7, wherein the portion (8) is one of circular, oval and polygonal when viewed from above.

9. In the method according to claim 1, wherein a pressure medium is applied to a side of the substrate (4) remote from the protective layer (5).

10. In the method according to claim 1, wherein a formation of the substrate arching and a detachment of the substrate from the carrying body (2) are achieved by controlling a pressure of the medium in a cavity between the substrate (4) and the carrying body (2).

11. In the method according to claim 4, wherein the flow apertures (3, 7) are configured as overpressure lines and the grooves are configured as negative pressure lines.

12. In the method according to claim 4, wherein the portion (8) is one of circular, oval and polygonal when viewed from above.